

Welcome to [E-XFL.COM](http://E-XFL.COM)

### What is "[Embedded - Microcontrollers](#)"?

"[Embedded - Microcontrollers](#)" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

### Applications of "[Embedded - Microcontrollers](#)"

#### Details


Product Status	Active
Core Processor	HC08
Core Size	8-Bit
Speed	8MHz
Connectivity	-
Peripherals	LVD, POR, PWM
Number of I/O	13
Program Memory Size	1.5KB (1.5K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	128 x 8
Voltage - Supply (Vcc/Vdd)	2.7V ~ 5.5V
Data Converters	A/D 4x8b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	16-TSSOP (0.173", 4.40mm Width)
Supplier Device Package	16-TSSOP
Purchase URL	<a href="https://www.e-xfl.com/pro/item?MUrl=&amp;PartUrl=mc68hc908qy2cdte">https://www.e-xfl.com/pro/item?MUrl=&amp;PartUrl=mc68hc908qy2cdte</a>

## List of Chapters

Chapter 1 General Description . . . . .	17
Chapter 2 Memory . . . . .	25
Chapter 3 Analog-to-Digital Converter (ADC) . . . . .	41
Chapter 4 Auto Wakeup Module (AWU) . . . . .	49
Chapter 5 Configuration Register (CONFIG) . . . . .	53
Chapter 6 Computer Operating Properly (COP) . . . . .	57
Chapter 7 Central Processor Unit (CPU) . . . . .	61
Chapter 8 External Interrupt (IRQ) . . . . .	73
Chapter 9 Keyboard Interrupt Module (KBI) . . . . .	79
Chapter 10 Low-Voltage Inhibit (LVI) . . . . .	85
Chapter 11 Oscillator Module (OSC) . . . . .	89
Chapter 12 Input/Output Ports (PORTS) . . . . .	97
Chapter 13 System Integration Module (SIM) . . . . .	103
Chapter 14 Timer Interface Module (TIM) . . . . .	119
Chapter 15 Development Support . . . . .	133
Chapter 16 Electrical Specifications . . . . .	149
Chapter 17 Ordering Information and Mechanical Specifications . . . . .	165



**Table 2-1. Vector Addresses**

Vector Priority	Vector	Address	Vector
Lowest  Highest	IF15	\$FFDE	ADC conversion complete vector (high)
		\$FFDF	ADC conversion complete vector (low)
	IF14	\$FFE0	Keyboard vector (high)
		\$FFE1	Keyboard vector (low)
	IF13 ↓ IF6	—	Not used
	IF5	\$FFF2	TIM overflow vector (high)
		\$FFF3	TIM overflow vector (low)
	IF4	\$FFF4	TIM Channel 1 vector (high)
		\$FFF5	TIM Channel 1 vector (low)
	IF3	\$FFF6	TIM Channel 0 vector (high)
		\$FFF7	TIM Channel 0 vector (low)
	IF2	—	Not used
	IF1	\$FFFA	$\overline{\text{IRQ}}$ vector (high)
		\$FFFB	$\overline{\text{IRQ}}$ vector (low)
	—	\$FFFC	SWI vector (high)
		\$FFFD	SWI vector (low)
	—	\$FFFE	Reset vector (high)
		\$FFFF	Reset vector (low)

## 2.5 Random-Access Memory (RAM)

Addresses \$0080–\$00FF are RAM locations. The location of the stack RAM is programmable. The 16-bit stack pointer allows the stack to be anywhere in the 64-Kbyte memory space.

**NOTE**

*For correct operation, the stack pointer must point only to RAM locations.*

Before processing an interrupt, the central processor unit (CPU) uses five bytes of the stack to save the contents of the CPU registers.

**NOTE**

*For M6805, M146805, and M68HC05 compatibility, the H register is not stacked.*

During a subroutine call, the CPU uses two bytes of the stack to store the return address. The stack pointer decrements during pushes and increments during pulls.

**NOTE**

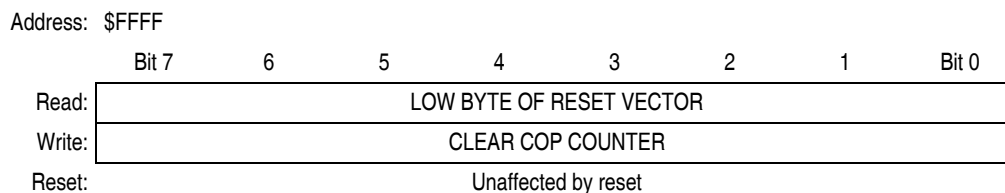
*Be careful when using nested subroutines. The CPU may overwrite data in the RAM during a subroutine or during the interrupt stacking operation.*

### 6.3.7 COPRS (COP Rate Select)

The COPRS signal reflects the state of the COP rate select bit (COPRS) in the configuration register 1 (CONFIG1). See [Chapter 5 Configuration Register \(CONFIG\)](#).

## 6.4 COP Control Register

The COP control register (COPCTL) is located at address \$FFFF and overlaps the reset vector. Writing any value to \$FFFF clears the COP counter and starts a new timeout period. Reading location \$FFFF returns the low byte of the reset vector.



**Figure 6-2. COP Control Register (COPCTL)**

## 6.5 Interrupts

The COP does not generate CPU interrupt requests.

## 6.6 Monitor Mode

The COP is disabled in monitor mode when  $V_{TST}$  is present on the  $\overline{IRQ}$  pin.

## 6.7 Low-Power Modes

The WAIT and STOP instructions put the MCU in low power-consumption standby modes.

### 6.7.1 Wait Mode

The COP continues to operate during wait mode. To prevent a COP reset during wait mode, periodically clear the COP counter.

### 6.7.2 Stop Mode

Stop mode turns off the BUSCLKX4 input to the COP and clears the SIM counter. Service the COP immediately before entering or after exiting stop mode to ensure a full COP timeout period after entering or exiting stop mode.

## 6.8 COP Module During Break Mode

The COP is disabled during a break interrupt with monitor mode when BDCOP bit is set in break auxiliary register (BRKAR).



### 7.3.5 Condition Code Register

The 8-bit condition code register contains the interrupt mask and five flags that indicate the results of the instruction just executed. Bits 6 and 5 are set permanently to 1. The following paragraphs describe the functions of the condition code register.

	Bit 7	6	5	4	3	2	1	Bit 0
Read:	V	1	1	H	I	N	Z	C
Write:								
Reset:	X	1	1	X	1	X	X	X

X = Indeterminate

**Figure 7-6. Condition Code Register (CCR)**

#### V — Overflow Flag

The CPU sets the overflow flag when a two's complement overflow occurs. The signed branch instructions BGT, BGE, BLE, and BLT use the overflow flag.

- 1 = Overflow
- 0 = No overflow

#### H — Half-Carry Flag

The CPU sets the half-carry flag when a carry occurs between accumulator bits 3 and 4 during an add-without-carry (ADD) or add-with-carry (ADC) operation. The half-carry flag is required for binary-coded decimal (BCD) arithmetic operations. The DAA instruction uses the states of the H and C flags to determine the appropriate correction factor.

- 1 = Carry between bits 3 and 4
- 0 = No carry between bits 3 and 4

#### I — Interrupt Mask

When the interrupt mask is set, all maskable CPU interrupts are disabled. CPU interrupts are enabled when the interrupt mask is cleared. When a CPU interrupt occurs, the interrupt mask is set automatically after the CPU registers are saved on the stack, but before the interrupt vector is fetched.

- 1 = Interrupts disabled
- 0 = Interrupts enabled

**NOTE**

*To maintain M6805 Family compatibility, the upper byte of the index register (H) is not stacked automatically. If the interrupt service routine modifies H, then the user must stack and unstack H using the PSHH and PULH instructions.*

After the I bit is cleared, the highest-priority interrupt request is serviced first.

A return-from-interrupt (RTI) instruction pulls the CPU registers from the stack and restores the interrupt mask from the stack. After any reset, the interrupt mask is set and can be cleared only by the clear interrupt mask software instruction (CLI).

#### N — Negative Flag

The CPU sets the negative flag when an arithmetic operation, logic operation, or data manipulation produces a negative result, setting bit 7 of the result.

- 1 = Negative result
- 0 = Non-negative result

Table 7-1. Instruction Set Summary (Sheet 6 of 6)

Source Form	Operation	Description	Effect on CCR					Address Mode	Opcode	Operand	Cycles	
			V	H	I	N	Z					C
SWI	Software Interrupt	PC ← (PC) + 1; Push (PCL) SP ← (SP) - 1; Push (PCH) SP ← (SP) - 1; Push (X) SP ← (SP) - 1; Push (A) SP ← (SP) - 1; Push (CCR) SP ← (SP) - 1; I ← 1 PCH ← Interrupt Vector High Byte PCL ← Interrupt Vector Low Byte	-	-	1	-	-	-	INH	83		9
TAP	Transfer A to CCR	CCR ← (A)	↑	↑	↑	↑	↑	↑	INH	84		2
TAX	Transfer A to X	X ← (A)	-	-	-	-	-	-	INH	97		1
TPA	Transfer CCR to A	A ← (CCR)	-	-	-	-	-	-	INH	85		1
TST <i>opr</i> TSTA TSTX TST <i>opr,X</i> TST ,X TST <i>opr,SP</i>	Test for Negative or Zero	(A) - \$00 or (X) - \$00 or (M) - \$00	0	-	-	↑	↑	-	DIR INH INH IX1 IX SP1	3D 4D 5D 6D 7D 9E6D	dd ff ff	3 1 1 3 2 4
TSX	Transfer SP to H:X	H:X ← (SP) + 1	-	-	-	-	-	-	INH	95		2
TXA	Transfer X to A	A ← (X)	-	-	-	-	-	-	INH	9F		1
TXS	Transfer H:X to SP	(SP) ← (H:X) - 1	-	-	-	-	-	-	INH	94		2
WAIT	Enable Interrupts; Wait for Interrupt	I bit ← 0; Inhibit CPU clocking until interrupted	-	-	0	-	-	-	INH	8F		1

- |       |   |            |   |
|-------|---|------------|---|
| A     | Accumulator   | <i>n</i>   | Any bit                                     |
| C     | Carry/borrow bit  | <i>opr</i> | Operand (one or two bytes)                  |
| CCR   | Condition code register   | PC         | Program counter                             |
| dd    | Direct address of operand   | PCH        | Program counter high byte                   |
| dd rr | Direct address of operand and relative offset of branch instruction | PCL        | Program counter low byte                    |
| DD    | Direct to direct addressing mode                                    | REL        | Relative addressing mode                    |
| DIR   | Direct addressing mode  | <i>rel</i> | Relative program counter offset byte        |
| DIX+  | Direct to indexed with post increment addressing mode               | rr         | Relative program counter offset byte        |
| ee ff | High and low bytes of offset in indexed, 16-bit offset addressing   | SP1        | Stack pointer, 8-bit offset addressing mode |
| EXT   | Extended addressing mode  | SP2        | Stack pointer 16-bit offset addressing mode |
| ff    | Offset byte in indexed, 8-bit offset addressing                     | SP         | Stack pointer                               |
| H     | Half-carry bit  | U          | Undefined                                   |
| H     | Index register high byte  | V          | Overflow bit                                |
| hh ll | High and low bytes of operand address in extended addressing        | X          | Index register low byte                     |
| I     | Interrupt mask  | Z          | Zero bit                                    |
| ii    | Immediate operand byte  | &          | Logical AND                                 |
| IMD   | Immediate source to direct destination addressing mode              |            | Logical OR                                  |
| IMM   | Immediate addressing mode   | ⊕          | Logical EXCLUSIVE OR                        |
| INH   | Inherent addressing mode  | ()         | Contents of                                 |
| IX    | Indexed, no offset addressing mode                                  | -( )       | Negation (two's complement)                 |
| IX+   | Indexed, no offset, post increment addressing mode                  | #          | Immediate value                             |
| IX+D  | Indexed with post increment to direct addressing mode               | «          | Sign extend                                 |
| IX1   | Indexed, 8-bit offset addressing mode                               | ←          | Loaded with                                 |
| IX1+  | Indexed, 8-bit offset, post increment addressing mode               | ?          | If  |
| IX2   | Indexed, 16-bit offset addressing mode                              | :          | Concatenated with                           |
| M     | Memory location   | ↑          | Set or cleared                              |
| N     | Negative bit  | —          | Not affected                                |

## 7.8 Opcode Map

See [Table 7-2](#).



# Chapter 9

## Keyboard Interrupt Module (KBI)

### 9.1 Introduction

The keyboard interrupt module (KBI) provides six independently maskable external interrupts, which are accessible via the PTA0–PTA5 pins.

### 9.2 Features

Features of the keyboard interrupt module include:

- Six keyboard interrupt pins with separate keyboard interrupt enable bits and one keyboard interrupt mask
- Software configurable pullup device if input pin is configured as input port bit
- Programmable edge-only or edge and level interrupt sensitivity
- Exit from low-power modes

### 9.3 Functional Description

The keyboard interrupt module controls the enabling/disabling of interrupt functions on the six port A pins. These six pins can be enabled/disabled independently of each other. Refer to [Figure 9-2](#).

#### 9.3.1 Keyboard Operation

Writing to the KBIE0–KBIE5 bits in the keyboard interrupt enable register (KBIER) independently enables or disables each port A pin as a keyboard interrupt pin. Enabling a keyboard interrupt pin in port A also enables its internal pullup device irrespective of PTAPUE<sub>x</sub> bits in the port A input pullup enable register (see [12.2.3 Port A Input Pullup Enable Register](#)). A logic 0 applied to an enabled keyboard interrupt pin latches a keyboard interrupt request.

A keyboard interrupt is latched when one or more keyboard interrupt inputs goes low after all were high. The MODEK bit in the keyboard status and control register controls the triggering mode of the keyboard interrupt.

- If the keyboard interrupt is edge-sensitive only, a falling edge on a keyboard interrupt input does not latch an interrupt request if another keyboard pin is already low. To prevent losing an interrupt request on one input because another input is still low, software can disable the latter input while it is low.
- If the keyboard interrupt is falling edge and low-level sensitive, an interrupt request is present as long as any keyboard interrupt input is low.

### 14.4.1 TIM Counter Prescaler

The TIM clock source is one of the seven prescaler outputs or the TIM clock pin, TCLK. The prescaler generates seven clock rates from the internal bus clock. The prescaler select bits, PS[2:0], in the TIM status and control register (TSC) select the TIM clock source.

### 14.4.2 Input Capture

With the input capture function, the TIM can capture the time at which an external event occurs. When an active edge occurs on the pin of an input capture channel, the TIM latches the contents of the TIM counter into the TIM channel registers, TCHxH:TCHxL. The polarity of the active edge is programmable. Input captures can generate TIM central processor unit (CPU) interrupt requests.

### 14.4.3 Output Compare

With the output compare function, the TIM can generate a periodic pulse with a programmable polarity, duration, and frequency. When the counter reaches the value in the registers of an output compare channel, the TIM can set, clear, or toggle the channel pin. Output compares can generate TIM CPU interrupt requests.

#### 14.4.3.1 Unbuffered Output Compare

Any output compare channel can generate unbuffered output compare pulses as described in [14.4.3 Output Compare](#). The pulses are unbuffered because changing the output compare value requires writing the new value over the old value currently in the TIM channel registers.

An unsynchronized write to the TIM channel registers to change an output compare value could cause incorrect operation for up to two counter overflow periods. For example, writing a new value before the counter reaches the old value but after the counter reaches the new value prevents any compare during that counter overflow period. Also, using a TIM overflow interrupt routine to write a new, smaller output compare value may cause the compare to be missed. The TIM may pass the new value before it is written.

Use the following methods to synchronize unbuffered changes in the output compare value on channel x:

- When changing to a smaller value, enable channel x output compare interrupts and write the new value in the output compare interrupt routine. The output compare interrupt occurs at the end of the current output compare pulse. The interrupt routine has until the end of the counter overflow period to write the new value.
- When changing to a larger output compare value, enable TIM overflow interrupts and write the new value in the TIM overflow interrupt routine. The TIM overflow interrupt occurs at the end of the current counter overflow period. Writing a larger value in an output compare interrupt routine (at the end of the current pulse) could cause two output compares to occur in the same counter overflow period.

#### 14.4.3.2 Buffered Output Compare

Channels 0 and 1 can be linked to form a buffered output compare channel whose output appears on the TCH0 pin. The TIM channel registers of the linked pair alternately control the output.

Setting the MS0B bit in TIM channel 0 status and control register (TSC0) links channel 0 and channel 1. The output compare value in the TIM channel 0 registers initially controls the output on the TCH0 pin. Writing to the TIM channel 1 registers enables the TIM channel 1 registers to synchronously control the output after the TIM overflows. At each subsequent overflow, the TIM channel registers (0 or 1) that

### 14.4.4.3 PWM Initialization

To ensure correct operation when generating unbuffered or buffered PWM signals, use the following initialization procedure:

1. In the TIM status and control register (TSC):
  - a. Stop the TIM counter by setting the TIM stop bit, TSTOP.
  - b. Reset the TIM counter and prescaler by setting the TIM reset bit, TRST.
2. In the TIM counter modulo registers (TMODH:TMODL), write the value for the required PWM period.
3. In the TIM channel x registers (TCHxH:TCHxL), write the value for the required pulse width.
4. In TIM channel x status and control register (TSCx):
  - a. Write 0:1 (for unbuffered output compare or PWM signals) or 1:0 (for buffered output compare or PWM signals) to the mode select bits, MSxB:MSxA. See [Table 14-3](#).
  - b. Write 1 to the toggle-on-overflow bit, TOVx.
  - c. Write 1:0 (polarity 1 — to clear output on compare) or 1:1 (polarity 0 — to set output on compare) to the edge/level select bits, ELSxB:ELSxA. The output action on compare must force the output to the complement of the pulse width level. See [Table 14-3](#).

#### NOTE

*In PWM signal generation, do not program the PWM channel to toggle on output compare. Toggling on output compare prevents reliable 0% duty cycle generation and removes the ability of the channel to self-correct in the event of software error or noise. Toggling on output compare can also cause incorrect PWM signal generation when changing the PWM pulse width to a new, much larger value.*

5. In the TIM status control register (TSC), clear the TIM stop bit, TSTOP.

Setting MS0B links channels 0 and 1 and configures them for buffered PWM operation. The TIM channel 0 registers (TCH0H:TCH0L) initially control the buffered PWM output. TIM status control register 0 (TSCR0) controls and monitors the PWM signal from the linked channels. MS0B takes priority over MS0A.

Clearing the toggle-on-overflow bit, TOVx, inhibits output toggles on TIM overflows. Subsequent output compares try to force the output to a state it is already in and have no effect. The result is a 0% duty cycle output.

Setting the channel x maximum duty cycle bit (CHxMAX) and setting the TOVx bit generates a 100% duty cycle output. See [14.9.4 TIM Channel Status and Control Registers](#).

## 14.5 Interrupts

The following TIM sources can generate interrupt requests:

- TIM overflow flag (TOF) — The TOF bit is set when the TIM counter reaches the modulo value programmed in the TIM counter modulo registers. The TIM overflow interrupt enable bit, TOIE, enables TIM overflow CPU interrupt requests. TOF and TOIE are in the TIM status and control register.
- TIM channel flags (CH1F:CH0F) — The CHxF bit is set when an input capture or output compare occurs on channel x. Channel x TIM CPU interrupt requests are controlled by the channel x interrupt enable bit, CHxIE. Channel x TIM CPU interrupt requests are enabled when CHxIE = 1. CHxF and CHxIE are in the TIM channel x status and control register.

# Chapter 15

## Development Support

### 15.1 Introduction

This section describes the break module, the monitor read-only memory (MON), and the monitor mode entry methods.

### 15.2 Break Module (BRK)

The break module can generate a break interrupt that stops normal program flow at a defined address to enter a background program.

Features include:

- Accessible input/output (I/O) registers during the break Interrupt
- Central processor unit (CPU) generated break interrupts
- Software-generated break interrupts
- Computer operating properly (COP) disabling during break interrupts

#### 15.2.1 Functional Description

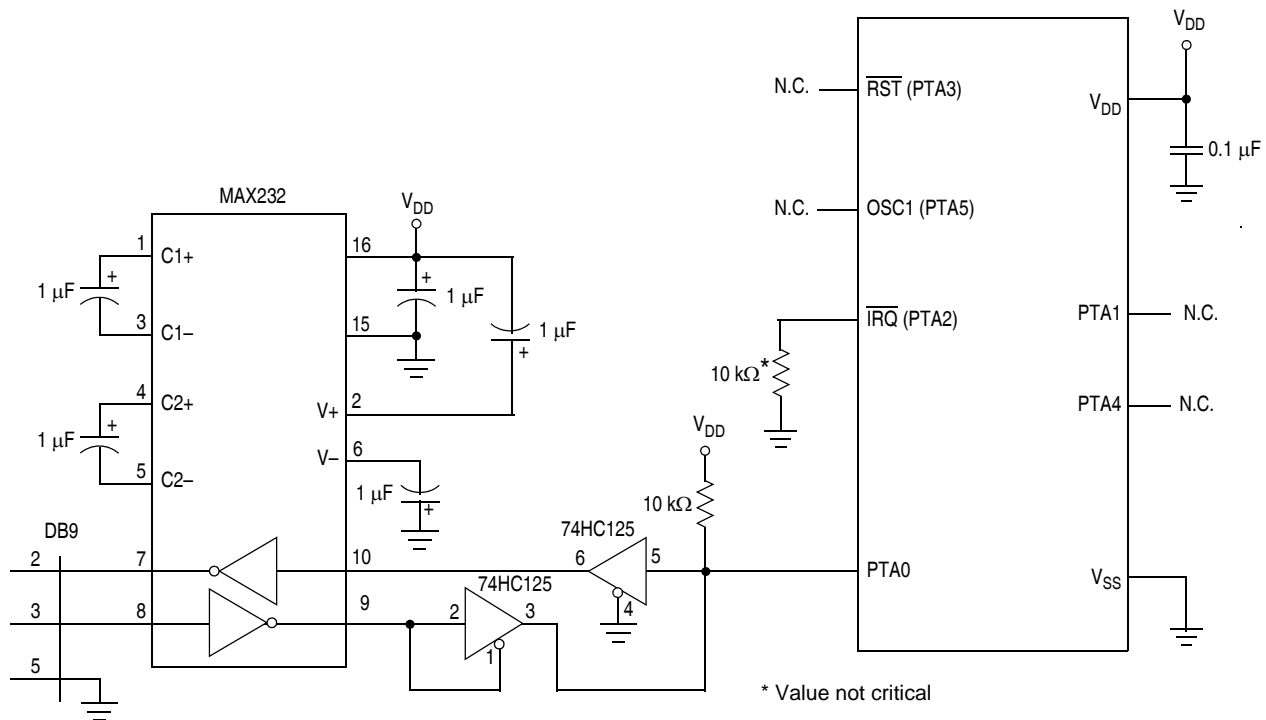
When the internal address bus matches the value written in the break address registers, the break module issues a breakpoint signal ( $\overline{\text{BKPT}}$ ) to the system integration module (SIM). The SIM then causes the CPU to load the instruction register with a software interrupt instruction (SWI). The program counter vectors to \$FFFC and \$FFFD (\$FEFC and \$FEFD in monitor mode).

The following events can cause a break interrupt to occur:

- A CPU generated address (the address in the program counter) matches the contents of the break address registers.
- Software writes a 1 to the BRKA bit in the break status and control register.

When a CPU generated address matches the contents of the break address registers, the break interrupt is generated. A return-from-interrupt instruction (RTI) in the break routine ends the break interrupt and returns the microcontroller unit (MCU) to normal operation.

Figure 15-2 shows the structure of the break module.



**Figure 15-12. Monitor Mode Circuit (Internal Clock, No High Voltage)**

Simple monitor commands can access any memory address. In monitor mode, the MCU can execute code downloaded into RAM by a host computer while most MCU pins retain normal operating mode functions. All communication between the host computer and the MCU is through the PTA0 pin. A level-shifting and multiplexing interface is required between PTA0 and the host computer. PTA0 is used in a wired-OR configuration and requires a pullup resistor.

The monitor code has been updated from previous versions of the monitor code to allow enabling the internal oscillator to generate the internal clock. This addition, which is enabled when  $\overline{\text{IRQ}}$  is held low out of reset, is intended to support serial communication/programming at 9600 baud in monitor mode by using the internal oscillator, and the internal oscillator user trim value OSCTRIM (FLASH location \$FFC0, if programmed) to generate the desired internal frequency (3.2 MHz). Since this feature is enabled only when  $\overline{\text{IRQ}}$  is held low out of reset, it cannot be used when the reset vector is programmed (i.e., the value is not \$FFFF) because entry into monitor mode in this case requires  $V_{\text{TST}}$  on  $\overline{\text{IRQ}}$ . The  $\overline{\text{IRQ}}$  pin must remain low during this monitor session in order to maintain communication.

Table 15-1 shows the pin conditions for entering monitor mode. As specified in the table, monitor mode may be entered after a power-on reset (POR) and will allow communication at 9600 baud provided one of the following sets of conditions is met:

- If \$FFFE and \$FFFF do not contain \$FF (programmed state):
  - The external clock is 9.8304 MHz
  - $\overline{\text{IRQ}} = V_{\text{TST}}$
- If \$FFFE and \$FFFF contain \$FF (erased state):
  - The external clock is 9.8304 MHz
  - $\overline{\text{IRQ}} = V_{\text{DD}}$  (this can be implemented through the internal  $\overline{\text{IRQ}}$  pullup)
- If \$FFFE and \$FFFF contain \$FF (erased state):
  - $\overline{\text{IRQ}} = V_{\text{SS}}$  (internal oscillator is selected, no external clock required)

## 16.16 Memory Characteristics

Characteristic	Symbol	Min	Typ	Max	Unit
RAM data retention voltage	$V_{RDR}$	1.3	—	—	V
FLASH program bus clock frequency	—	1	—	—	MHz
FLASH read bus clock frequency	$f_{Read}^{(1)}$	0	—	8 M	Hz
FLASH page erase time <1 k cycles >1 k cycles	$t_{Erase}$	0.9 3.6	1 4	1.1 5.5	ms
FLASH mass erase time	$t_{MErase}$	4	—	—	ms
FLASH PGM/ERASE to HVEN setup time	$t_{NVS}$	10	—	—	$\mu$ s
FLASH high-voltage hold time	$t_{NVH}$	5	—	—	$\mu$ s
FLASH high-voltage hold time (mass erase)	$t_{NVHL}$	100	—	—	$\mu$ s
FLASH program hold time	$t_{PGS}$	5	—	—	$\mu$ s
FLASH program time	$t_{PROG}$	30	—	40	$\mu$ s
FLASH return to read time	$t_{RCV}^{(2)}$	1	—	—	$\mu$ s
FLASH cumulative program HV period	$t_{HV}^{(3)}$	—	—	4	ms
FLASH endurance <sup>(4)</sup>	—	10 k	100 k	—	Cycles
FLASH data retention time <sup>(5)</sup>	—	15	100	—	Years

- $f_{Read}$  is defined as the frequency range for which the FLASH memory can be read.
- $t_{RCV}$  is defined as the time it needs before the FLASH can be read after turning off the high voltage charge pump, by clearing HVEN to 0.
- $t_{HV}$  is defined as the cumulative high voltage programming time to the same row before next erase.  
 $t_{HV}$  must satisfy this condition:  $t_{NVS} + t_{NVH} + t_{PGS} + (t_{PROG} \times 32) \leq t_{HV}$  maximum.
- Typical endurance was evaluated for this product family. For additional information on how Freescale defines *Typical Endurance*, please refer to Engineering Bulletin EB619.
- Typical data retention values are based on intrinsic capability of the technology measured at high temperature and de-rated to 25°C using the Arrhenius equation. For additional information on how Freescale defines *Typical Data Retention*, please refer to Engineering Bulletin EB618.





© FREESCALE SEMICONDUCTOR, INC. ALL RIGHTS RESERVED.  
 ELECTRONIC VERSIONS ARE UNCONTROLLED EXCEPT WHEN ACCESSED  
 DIRECTLY FROM THE DOCUMENT CONTROL REPOSITORY. PRINTED  
 VERSIONS ARE UNCONTROLLED EXCEPT WHEN STAMPED "CONTROLLED  
 COPY" IN RED.

**MECHANICAL OUTLINES  
 DICTIONARY**

DOCUMENT NO: 98ASH70107A

PAGE: 968

DO NOT SCALE THIS DRAWING

REV: A

NOTES:

1. DIMENSIONS AND TOLERANCES PER ASME Y14.5-1994.

2. CONTROLLING DIMENSION: MILLIMETER.

3. DIMENSIONS DO NOT INCLUDE MOLD FLASH OR PROTRUSIONS AND ARE MEASURED AT THE PARTING LINE. MOLD FLASH OR PROTRUSIONS SHALL NOT EXCEED 0.15mm PER SIDE.

4. TERMINAL NUMBERS ARE SHOWN FOR REFERENCE ONLY.

5. THE LEAD WIDTH DIMENSION DOES NOT INCLUDE DAMBAR PROTRUSION SHALL BE 0.08mm TOTAL IN EXCESS OF THE LEAD WIDTH DIMENSION AT MAXIMUM MATERIAL CONDITION. DAMBAR CANNOT BE LOCATED ON THE LOWER RADIUS OR THE FOOT. MINIMUM SPACE BETWEEN PROTRUSIONS AND ADJACENT LEAD TO BE 0.46mm.

TITLE:

8 LEAD MFP

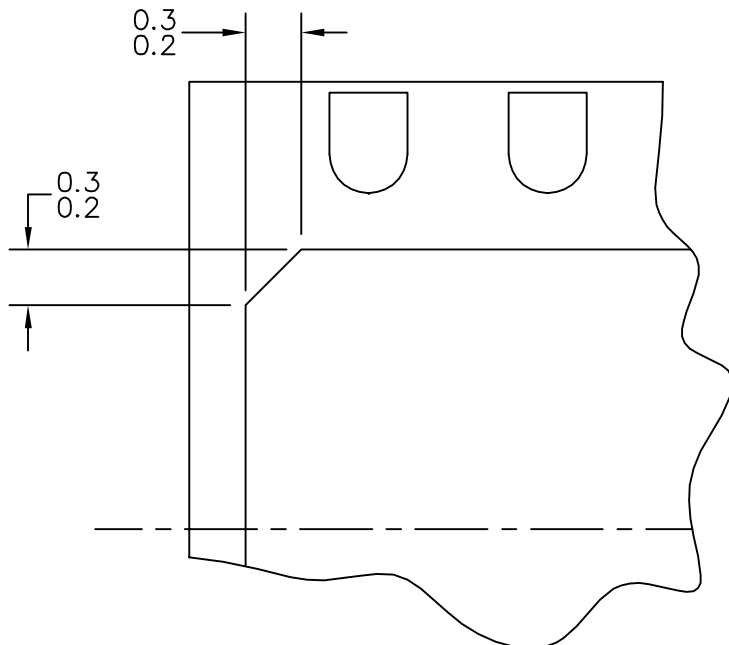
CASE NUMBER: 968-02

STANDARD: EIAJ

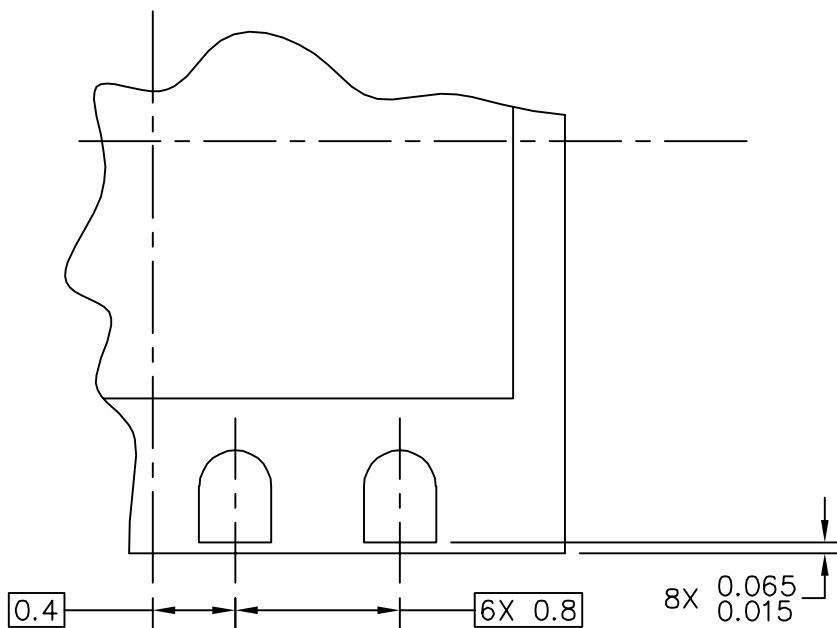
PACKAGE CODE: 6003

SHEET: 3 OF 4





DETAIL M  
 BACKSIDE PIN 1 INDEX



DETAIL N

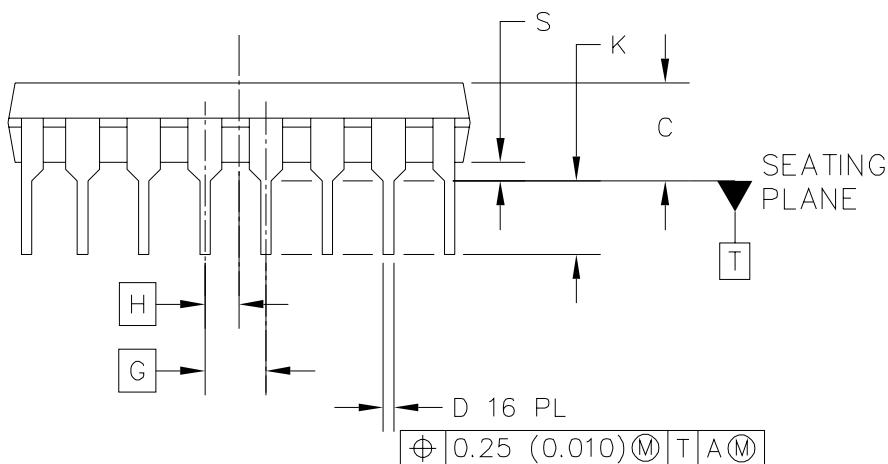
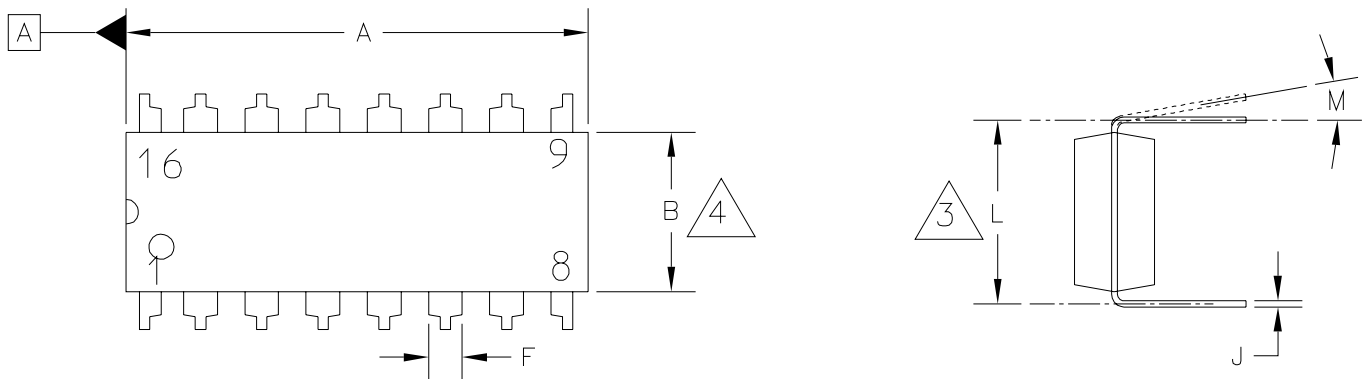
TITLE: THERMALLY ENHANCED DUAL  
 FLAT NO LEAD PACKAGE (DFN)  
 8 TERMINAL, 0.8 PITCH (4 X 4 X 1)

CASE NUMBER: 1452-01

STANDARD: NON-JEDEC

PACKAGE CODE: 6165

SHEET: 3 OF 5



TITLE:

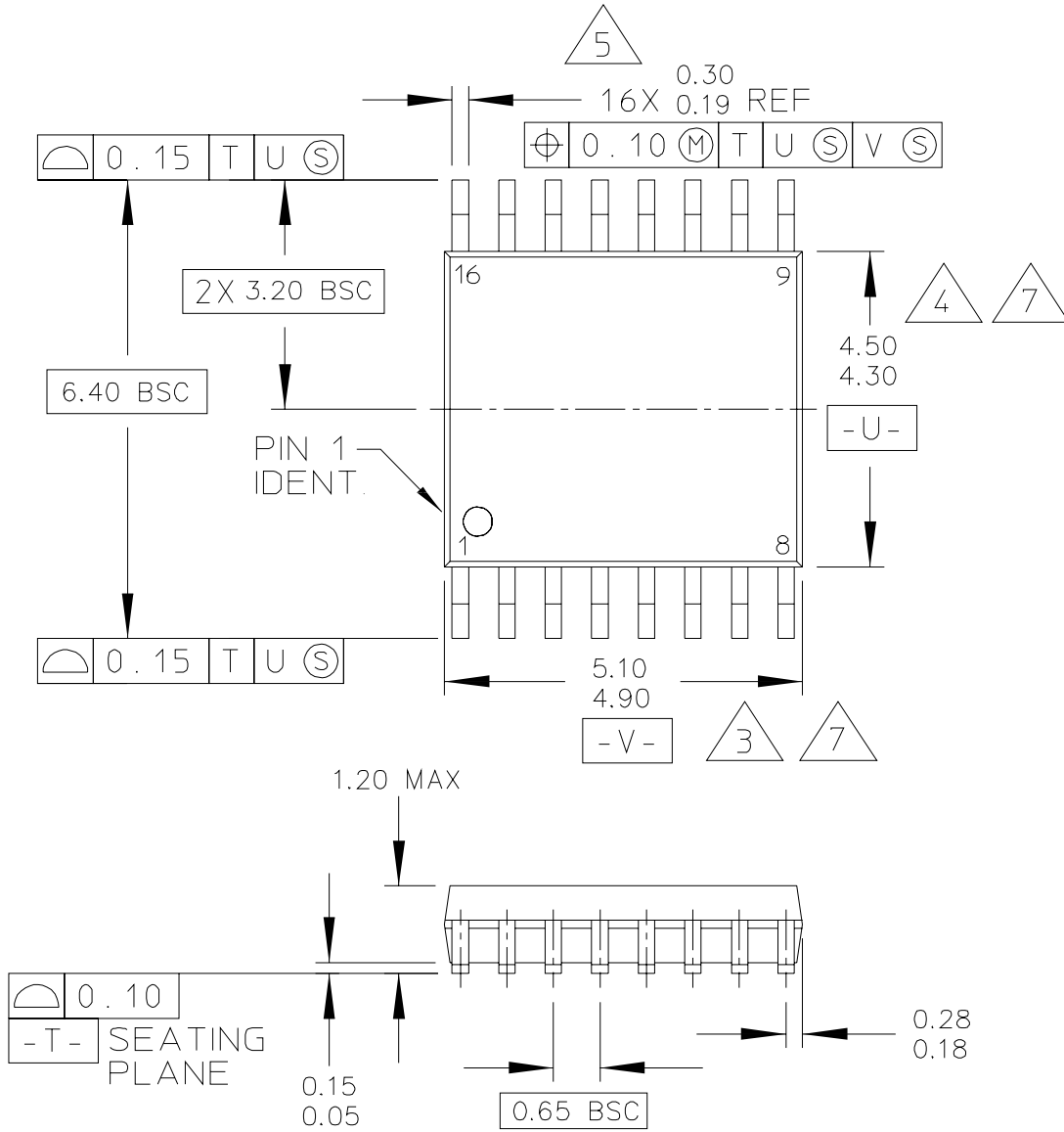
16 LD PDIP

CASE NUMBER: 648-08

STANDARD: NON-JEDEC

PACKAGE CODE: 0006

SHEET: 1 OF 4



TITLE:  
 16 LD TSSOP, PITCH 0.65MM

CASE NUMBER: 948F-01

STANDARD: JEDEC

PACKAGE CODE: 6117

SHEET: 1 OF 4



© FREESCALE SEMICONDUCTOR, INC. ALL RIGHTS RESERVED.  
 ELECTRONIC VERSIONS ARE UNCONTROLLED EXCEPT WHEN ACCESSED  
 DIRECTLY FROM THE DOCUMENT CONTROL REPOSITORY. PRINTED  
 VERSIONS ARE UNCONTROLLED EXCEPT WHEN STAMPED "CONTROLLED  
 COPY" IN RED.

MECHANICAL OUTLINES  
 DICTIONARY

DOCUMENT NO: 98ASH70247A

PAGE: 948F

DO NOT SCALE THIS DRAWING

REV: B

NOTES:

1. CONTROLLING DIMENSION: MILLIMETER
2. DIMENSIONS AND TOLERANCES PER ANSI Y14.5M-1982.
3. DIMENSION DOES NOT INCLUDE MOLD FLASH, PROTRUSIONS OR GATE BURRS. MOLD FLASH OR GATE BURRS SHALL NOT EXCEED 0.15 PER SIDE.
4. DIMENSION DOES NOT INCLUDE INTERLEAD FLASH OR PROTRUSION. INTERLEAD FLASH OR PROTRUSION SHALL NOT EXCEED 0.25 PER SIDE.
5. DIMENSION DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.08 TOTAL IN EXCESS OF THE DIMENSION AT MAXIMUM MATERIAL CONDITION.
6. TERMINAL NUMBERS ARE SHOWN FOR REFERENCE ONLY.
7. DIMENSIONS ARE TO BE DETERMINED AT DATUM PLANE -W-.

TITLE:  
 16 LD TSSOP, PITCH 0.65MM

CASE NUMBER: 948F-01

STANDARD: JEDEC

PACKAGE CODE: 6117

SHEET: 3 OF 4

## **How to Reach Us:**

### **Home Page:**

[www.freescale.com](http://www.freescale.com)

### **E-mail:**

[support@freescale.com](mailto:support@freescale.com)

### **USA/Europe or Locations Not Listed:**

Freescale Semiconductor  
Technical Information Center, CH370  
1300 N. Alma School Road  
Chandler, Arizona 85224  
+1-800-521-6274 or +1-480-768-2130  
[support@freescale.com](mailto:support@freescale.com)

### **Europe, Middle East, and Africa:**

Freescale Halbleiter Deutschland GmbH  
Technical Information Center  
Schatzbogen 7  
81829 Muenchen, Germany  
+44 1296 380 456 (English)  
+46 8 52200080 (English)  
+49 89 92103 559 (German)  
+33 1 69 35 48 48 (French)  
[support@freescale.com](mailto:support@freescale.com)

### **Japan:**

Freescale Semiconductor Japan Ltd.  
Headquarters  
ARCO Tower 15F  
1-8-1, Shimo-Meguro, Meguro-ku,  
Tokyo 153-0064  
Japan  
0120 191014 or +81 3 5437 9125  
[support.japan@freescale.com](mailto:support.japan@freescale.com)

### **Asia/Pacific:**

Freescale Semiconductor Hong Kong Ltd.  
Technical Information Center  
2 Dai King Street  
Tai Po Industrial Estate  
Tai Po, N.T., Hong Kong  
+800 2666 8080  
[support.asia@freescale.com](mailto:support.asia@freescale.com)

### **For Literature Requests Only:**

Freescale Semiconductor Literature Distribution Center  
P.O. Box 5405  
Denver, Colorado 80217  
1-800-441-2447 or 303-675-2140  
Fax: 303-675-2150  
[LDCForFreescaleSemiconductor@hibbertgroup.com](mailto:LDCForFreescaleSemiconductor@hibbertgroup.com)

Information in this document is provided solely to enable system and software implementers to use Freescale Semiconductor products. There are no express or implied copyright licenses granted hereunder to design or fabricate any integrated circuits or integrated circuits based on the information in this document.

Freescale Semiconductor reserves the right to make changes without further notice to any products herein. Freescale Semiconductor makes no warranty, representation or guarantee regarding the suitability of its products for any particular purpose, nor does Freescale Semiconductor assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation consequential or incidental damages. "Typical" parameters that may be provided in Freescale Semiconductor data sheets and/or specifications can and do vary in different applications and actual performance may vary over time. All operating parameters, including "Typicals", must be validated for each customer application by customer's technical experts. Freescale Semiconductor does not convey any license under its patent rights nor the rights of others. Freescale Semiconductor products are not designed, intended, or authorized for use as components in systems intended for surgical implant into the body, or other applications intended to support or sustain life, or for any other application in which the failure of the Freescale Semiconductor product could create a situation where personal injury or death may occur. Should Buyer purchase or use Freescale Semiconductor products for any such unintended or unauthorized application, Buyer shall indemnify and hold Freescale Semiconductor and its officers, employees, subsidiaries, affiliates, and distributors harmless against all claims, costs, damages, and expenses, and reasonable attorney fees arising out of, directly or indirectly, any claim of personal injury or death associated with such unintended or unauthorized use, even if such claim alleges that Freescale Semiconductor was negligent regarding the design or manufacture of the part.

Freescale™ and the Freescale logo are trademarks of Freescale Semiconductor, Inc. All other product or service names are the property of their respective owners.

© Freescale Semiconductor, Inc. 2005–2010. All rights reserved.